expansion daughter cards are mounted in to the expansion connectors/slots on the computer main system board/mother board for expanding the system functions.-

Page 2, lines 10, delete "Electronic components always generate heat and EMI."

Page 2, lines 10, change "prior art of the PC" to - art of computer system design-

Page 2, lines 11, change "get better" to--having sufficient-

Page 2, lines 11-12, change "certain spacing and size is required." to -the computer systems are designed with certain spacing and size to meet the requirements-

Page 2, lines 13, change "avoid EMI or" to -solve EMI and/or-

Page 2, lines 14, change "in bigger size" to - in big size with sufficient spacing for the add-on expansion daughter cards-

Page 2, lines 14-15, change "But when the size of equipment is limited, the size of system board is therefore limited" to -However, in the application cases where the hardware system sizes are limited, and the installation environment is critical such as outdoor application, and especially when there are RF circuitries and components in the system,-

Page 2, lines 14, delete "Thus"

Page 2, lines 14, change "the expansion" to - add-on expansion daughter-

Page 2, lines 15-16, change "Whole system became unstable, if no interference proof means is implemented." to -Obviously, sufficient EMI proof means and heat conduction means are needed to be implemented, to ensure system function properly.-

Page 2, lines 17-25, change "When applying .. the system even cannot work." to --In the prior art of work, there are a variety of solutions to shield the components on a PCB, or shield a group of small assembly and then install them in a bigger PCB. Those designs provide a EMI shielding on the component level. However, on the system design level, especially, when an embedded computer system with different type of add-on expansion daughter cards, a system level EMI shield and heat conduction implementation is needed to ensure the whole system

performance as well as keep the flexibility of the adaptation of different types of add-on expansion daughter cards.--

Summary:

Page 2, lines 30-31, change "dual shield and heat sink expansion" to --dual complete EMI shield and heat conduction expansion apparatuses—

Page 2, lines 30, change "limit space" to --space limited—

Page 2, lines 32, change "houses" to – apparatuses—

Page 2, lines 32, change "EMI shield and heat conduct" to -- complete EMI shield and sufficient heat conduction—

Page 2, line 32 to page 3, line 1, change "daughter board inside" to --add-on expansion daughter cards inside them—

Page 3, line 1, change "housing solutions comprises" to --apparatus comprises—

Page 3, line 4, change "ground plate of" to --copper clad ground plane on--

Page 3, lines4-5, change ", which can connect with the add-on expansion board." to -- for connecting with add-on expansion daughter cards.—

Page 3, line 7, delete "shield"

Page 3, line 7, change "works" to –work-

Page 3, line 9, change "shields" to --completely shield—

Page 3, line 9-10, change "expansion board and outside house" to -- add-on expansion daughter card and the environment outside of the shield expansion apparatus—

Objects and Advantages

Page 3, line 19-21, change "highly stable …solution of current invention;" to --a computer system board with add-on expansion daughter cards in a space limited environment with high reliability and stability by the complete shield expansion apparatuses of current invention;--

Page 3, line 23, delete "shield"